

IN THE SPECIFICATION:

Please note that the paragraphs shown below are in clean form for clarity.

Please replace the sixth full paragraph on page 6 with the following:

Each of the IC dies 12A, 12B and 14A is a bare (unpackaged) die with one or more adjacent rows of bond pads 22 on an active side 24. In drawing FIGS. 1 and 2, the bond pads 22 of dies on the opposite side are not visible, being covered by a flowable, hardenable, polymeric glob-top 40. In drawing FIGS. 5 to 8, two rows of bond pads 22 are shown spanning the minor dimension 26 of the dies (See FIG. 1). Alternatively, the bond pads 22 may be configured in a row or rows anywhere on the active surface 24, but preferably along a centerline 42 of a major dimension 28 or minor dimension 26, or even at an oblique angle with the major dimension. Preferably, the dice 12, 14 should be aligned so that the rows of bond pads 22 are in a parallel, spaced apart relationship.

Please replace the sixth full paragraph on page 9 with the following:

Conductive patterns 34A, 34B are formed on sides 16,18, respectively, of the substrate 20, such as by a lithographic metallization process or by other methods known in the art. The conductive patterns 34A, 34B include conductors 35A having one end configured as a wire-connecting site 32 adjacent a through-slot 30, and the other end is configured for attachment to an input/output connection. Where the through-slot 30 is stepped, the wire-connecting sites 32 are positioned on the stepped surfaces 58.